



## SSC8134GS6A

### N-Channel Enhancement Mode MOSFET

#### ➤ Features

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
30V	$\pm 12V$	24m $\Omega$ @10V	8.5A
		26m $\Omega$ @4V5	
		31m $\Omega$ @2V5	

#### ➤ Description

This device uses advanced trench technology to provide excellent RDS(on) and low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

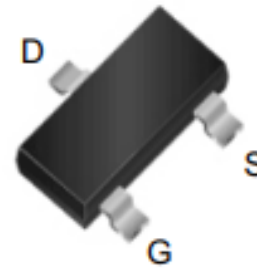
#### ➤ Applications

- Intelligent Lighting
- Load Switch
- Portable Devices
- DCDC Conversion

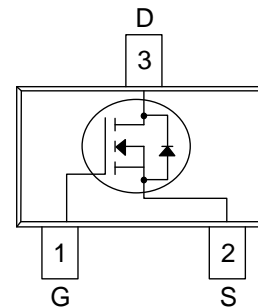
#### ➤ Ordering Information

Device	Package	Shipping
SSC8134GS6A	SOT-23-3L	3000/Reel

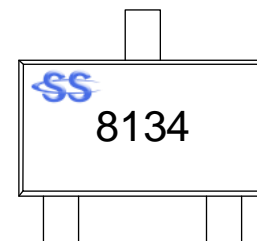
#### ➤ Pin configuration



**SOT-23-3L**



**Pin Configuration (Top View)**



**Marking**



➤ **Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	30	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current <sup>a</sup>	8.5	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	34	A
$P_D$	Power Dissipation <sup>c</sup>	2.72	W
$T_J$	Operation junction temperature	-55~150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55~150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	46	$^{\circ}\text{C}/\text{W}$

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.



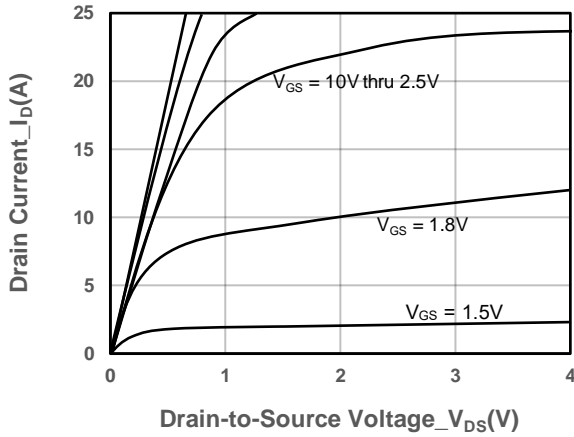
## SSC8134GS6A

### ➤ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

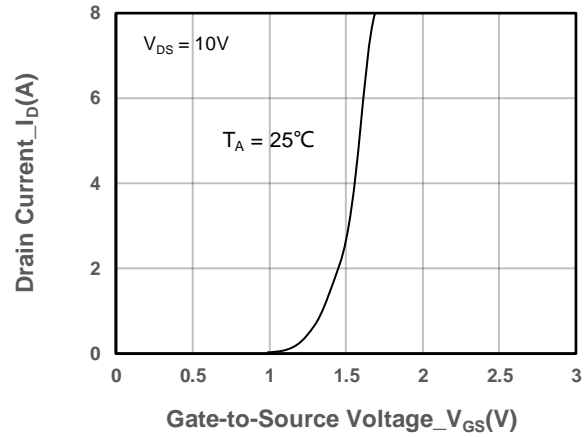
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.6	0.8	1.2	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6A		24	32	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A		26	35	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4A		31	40	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 2A		8		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 2A		0.7	1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		647		pF
Output Capacitance	C <sub>OSS</sub>			54		
Reverse Transfer Capacitance	C <sub>RSS</sub>			48		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> =3A  V <sub>DS</sub> = 15V, R <sub>G</sub> = 3Ω		8		ns
Rise Time	T <sub>r</sub>			13		
Turn-off Delay Time	T <sub>D(OFF)</sub>			25		
Fall Time	T <sub>f</sub>			10		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,  I <sub>D</sub> = 3A		16		nC
Gate to Source Charge	Q <sub>GS</sub>			1.9		
Gate to Drain Charge	Q <sub>GD</sub>			1.6		



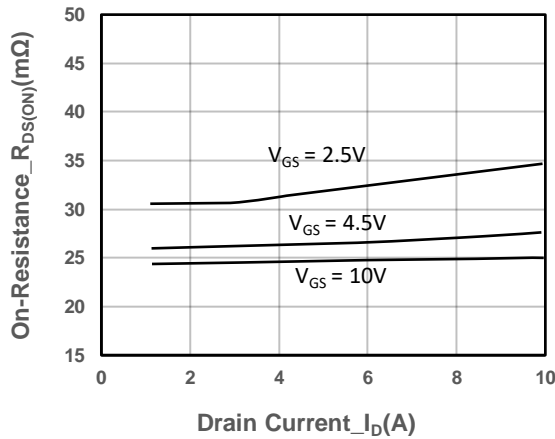
## ➤ Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



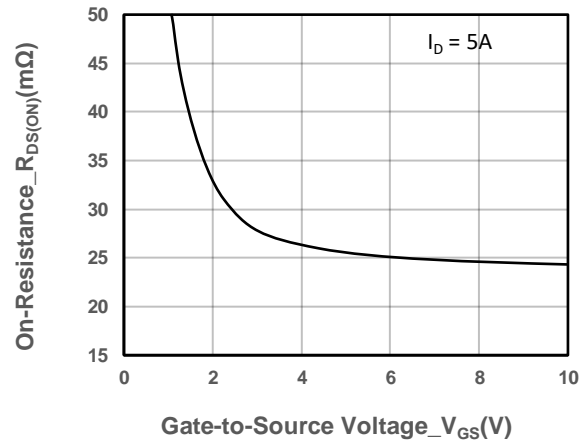
Output Characteristics



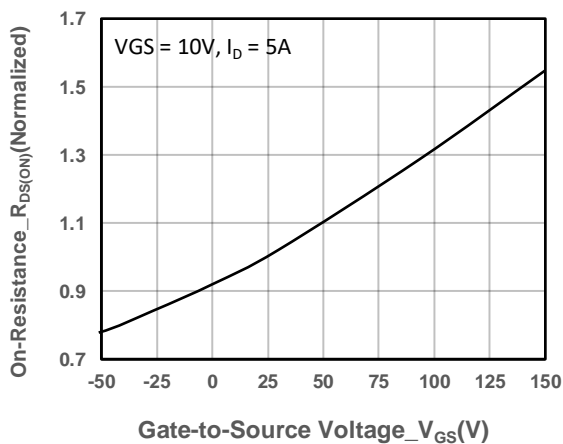
Transfer Characteristics



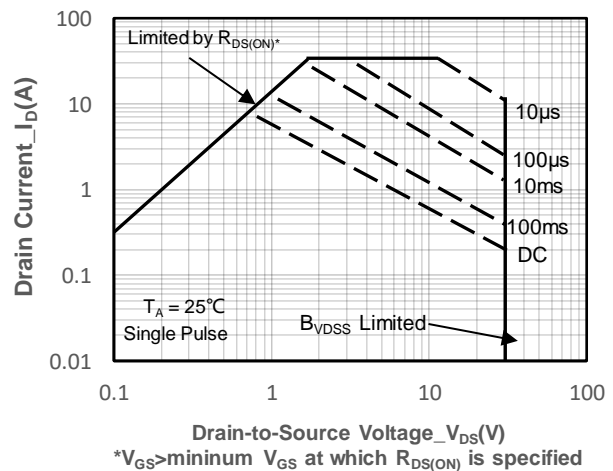
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



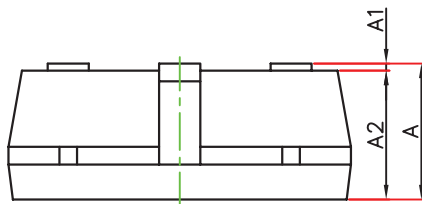
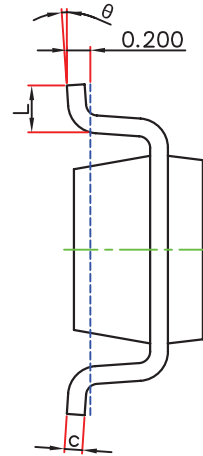
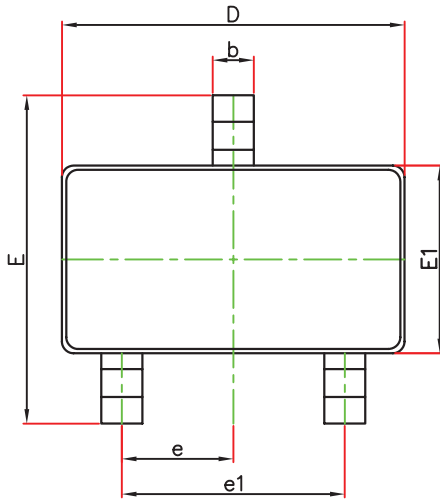
On-Resistance vs. Junction Temperature



Safe Operating Area vs. Junction-to-Ambient

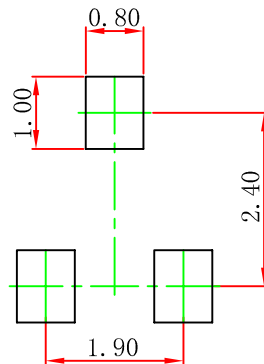


## ➤ Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°

## ➤ Recommended Pad outline (Unit: mm)





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